

HRB0103B

Silicon Schottky Barrier Diode for Low Voltage High Speed Switching, Rectifying

REJ03G0617-0200

(Previous: ADE-208-491A)

Rev.2.00 May 10, 2005

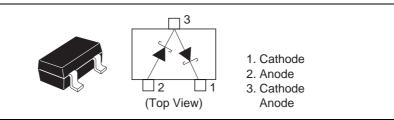
Features

- Low forward voltage drop and suitable for high efficiency forward current.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HRB0103B	E2	CMPAK	PTSP0003ZB-A
			(CMPAK)

Pin Arrangement



Absolute Maximum Ratings *1

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Average rectified current	lo*2	100	mA
Non-Repetitive peak forward surge current	I _{FSM} * ³	3	А
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

Notes: 1. Per one device.

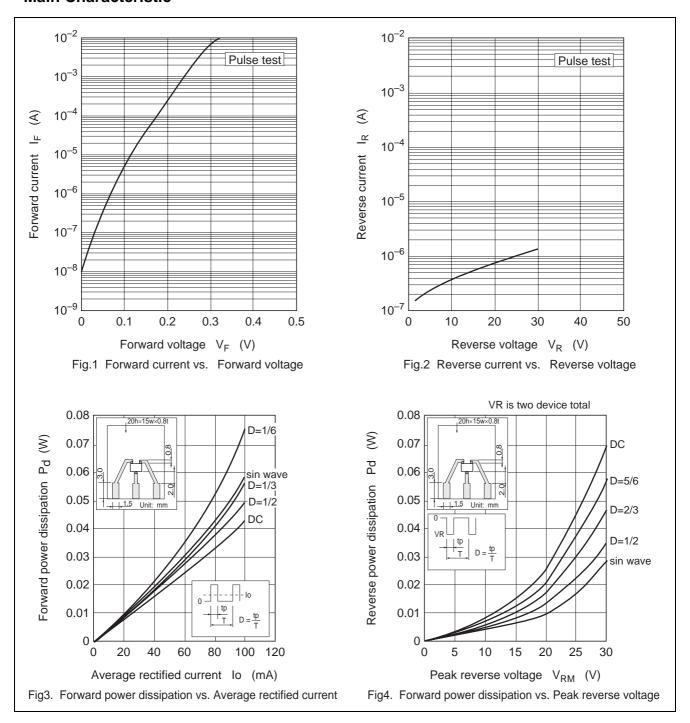
- 2. See Fig.5, Two device total.
- 3. 10 ms sine wave 1 pulse.

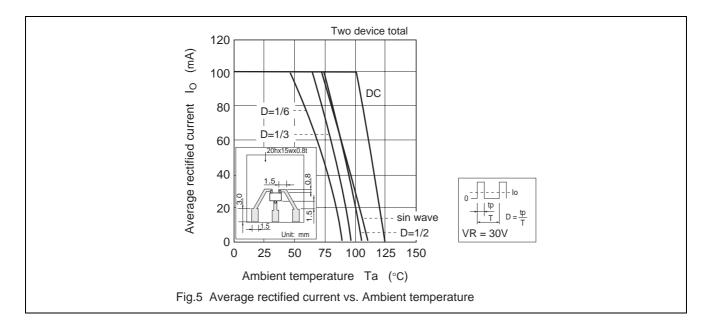
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

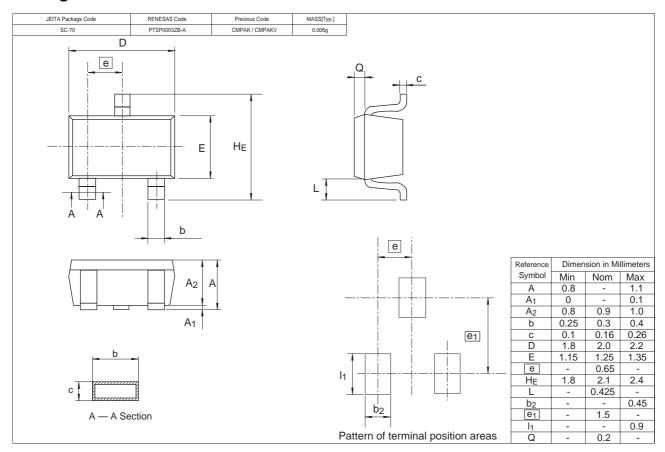
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V_{F}		_	0.44	V	I _F = 100 mA
Reverse current	I _R	_	_	50	μΑ	V _R = 30 V

Main Characteristic





Package Dimensions



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